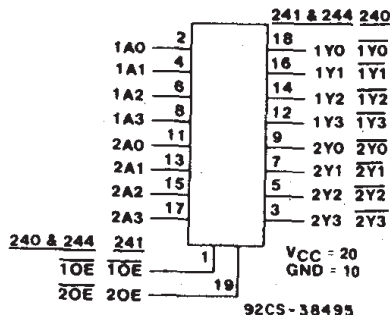


CD54/74AC240/241/244

CD54/74ACT240/241/244



Data sheet acquired from Harris Semiconductor
SCHS287B – Revised January 2004



FUNCTIONAL DIAGRAM & TERMINAL ASSIGNMENT

The RCA CD54/74AC240, CD54/74AC241, and CD54/74AC244 and the CD54/74ACT240, CD54/74ACT241, and CD54/74ACT244 3-state octal buffer/line drivers use the RCA ADVANCED CMOS technology. The CD54/74AC/ACT240 and CD54/74AC/ACT244 have active-LOW output enables ($\overline{10E}$, $\overline{20E}$). The CD54/74AC/ACT241 has one active-LOW ($\overline{10E}$) and one active-HIGH (20E) output enable.

The CD74AC240 and CD74ACT240 are supplied in 20-lead dual-in-line plastic packages (E suffix) and 20-lead small-outline packages (M and M96 suffixes). The CD74AC241 is supplied in 20-lead dual-in-line plastic packages (E suffix) and the CD74ACT241 is supplied in 20-lead dual-in-line plastic packages (E suffix) and 20-lead small-outline packages (M96 suffix). The CD74AC244 and CD74ACT244 are supplied in 20-lead dual-in-line plastic packages (E suffix), 20-lead small-outline packages (M and M96 suffixes), and 20-lead shrink small-outline packages (SM96 suffix). These package types are operable over the following temperature ranges: Commercial (0 to 70°C); Industrial (-40 to +85°C); and Extended Industrial/Military (-55 to +125°C).

The CD54AC240 and CD54AC244 and the CD54ACT240, CD54ACT241, and CD54ACT244 are supplied in 20-lead hermetic dual-in-line ceramic packages (F3A suffix) and are operable over the -55 to +125°C temperature range.

Octal Buffer/Line Drivers, 3-State

- CD54/74AC/ACT240 - Inverting
- CD54/74AC/ACT241 - Non-Inverting
- CD54/74AC/ACT244 - Non-Inverting

Type Features:

- Buffered inputs
- Typical propagation delay:
3.6 ns @ $V_{CC} = 5V$, $T_A = 25^\circ C$, $C_L = 50 pF$

Family Features:

- Exceeds 2-kV ESD Protection - MIL-STD-883, Method 3015
- SCR-Latch-up-resistant CMOS process and circuit design
- Speed of bipolar FAST*/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply
- ± 24 -mA output drive current
 - Fanout to 15 FAST* ICs
 - Drives 50-ohm transmission lines

*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

TRUTH TABLES

INPUTS		OUTPUT	
$\overline{10E}$, $\overline{20E}$	A	Y	
L	L	H	
L	H	L	
H	X	Z	

(AC/ACT240)

INPUTS		OUTPUT	
$\overline{10E}$, 20E	A	Y	
L	L	L	
L	H	H	
H	X	Z	

(AC/ACT244)

INPUTS		OUTPUT	INPUTS		OUTPUT
$\overline{10E}$	1A	1Y	20E	2A	2Y
L	L	L	L	X	Z
L	H	H	H	L	L
H	X	Z	H	H	H

(AC/ACT241)

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = HIGH Impedance

This data sheet is applicable to the CD54/74AC240, CD54ACT240, and CD54/74ACT241. The CD54/74AC241 were not acquired from Harris Semiconductor. See SCHS244 for information on the CD74ACT240, CD74AC244, and CD74ACT244.

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Technical Data

CD54/74AC240/241/244
CD54/74ACT240/241/244

STATIC ELECTRICAL CHARACTERISTICS: AC Series

CHARACTERISTICS	TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNITS	
				+25		-40 to +85		-55 to +125			
	V _I (V)	I _O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
High-Level Input Voltage V _{IH}			1.5	1.2	—	1.2	—	1.2	—	V	
			3	2.1	—	2.1	—	2.1	—		
			5.5	3.85	—	3.85	—	3.85	—		
Low-Level Input Voltage V _{IL}			1.5	—	0.3	—	0.3	—	0.3	V	
			3	—	0.9	—	0.9	—	0.9		
			5.5	—	1.65	—	1.65	—	1.65		
High-Level Output Voltage V _{OH}	V _{IH} or V _{IL}	-0.05	1.5	1.4	—	1.4	—	1.4	—	V	
			3	2.9	—	2.9	—	2.9	—		
			4.5	4.4	—	4.4	—	4.4	—		
			3	2.58	—	2.48	—	2.4	—		
			4.5	3.94	—	3.8	—	3.7	—		
			5.5	—	—	3.85	—	—	—		
			5.5	—	—	—	—	3.85	—		
Low-Level Output Voltage V _{OL}	V _{IH} or V _{IL}	0.05	1.5	—	0.1	—	0.1	—	0.1	V	
			3	—	0.1	—	0.1	—	0.1		
			4.5	—	0.1	—	0.1	—	0.1		
			12	3	—	0.36	—	0.44	—		0.5
			4.5	—	0.36	—	0.44	—	0.5		
			5.5	—	—	—	1.65	—	—		
			5.5	—	—	—	—	—	1.65		
Input Leakage Current I _I	V _{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA	
3-State Leakage Current I _{OZ}	V _{IH} or V _{IL}										
	V _O = V _{CC} or GND		5.5	—	±0.5	—	±5	—	±10	μA	
Quiescent Supply Current, MSI I _{CC}	V _{CC} or GND	0	5.5	—	8	—	80	—	160	μA	

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

CD54/74AC240/241/244 CD54/74ACT240/241/244

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

CHARACTERISTICS	TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNITS
				+25		-40 to +85		-55 to +125		
	V _I (V)	I _O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V _{IH}			4.5 to 5.5	2	—	2	—	2	—	V
Low-Level Input Voltage V _{IL}			4.5 to 5.5	—	0.8	—	0.8	—	0.8	V
High-Level Output Voltage V _{OH}	V _{IH} or V _{IL} #, *	-0.05	4.5	4.4	—	4.4	—	4.4	—	V
		-24	4.5	3.94	—	3.8	—	3.7	—	
		-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V _{OL}	V _{IH} or V _{IL} #, *	0.05	4.5	—	0.1	—	0.1	—	0.1	V
		24	4.5	—	0.36	—	0.44	—	0.5	
		75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I _I	V _{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current I _{OZ}	V _{IH} or V _{IL} V _O = V _{CC} or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI I _{CC}	V _{CC} or GND	0	5.5	—	8	—	80	—	160	μA
Additional Quiescent Supply Current per Input Pin TTL Inputs High 1 Unit Load ΔI _{CC}	V _{CC} -2.1		4.5 to 5.5	—	2.4	—	2.8	—	3	mA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLES

CD54/74ACT240	
INPUT	UNIT LOADS*
nA0 - A3	1.42
10E	0.83
20E	0.83

CD54/74ACT241	
INPUT	UNIT LOADS*
nA0 - A3	0.5
10E	0.83
20E	1.67

CD54/74ACT244	
INPUT	UNIT LOADS*
nA0 - A3	0.5
10E	0.83
20E	0.83

*Unit load is ΔI_{CC} limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

Technical Data

CD54/74AC240/241/244
CD54/74ACT240/241/244

SWITCHING CHARACTERISTICS: AC Series; $t_r, t_f = 3 \text{ ns}$, $C_L = 50 \text{ pF}$

CHARACTERISTICS	SYMBOL	V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Outputs AC240	t_{PLH}	1.5	—	82	—	90	ns
	t_{PHL}	3.3 [*]	2.6	9.2	2.5	10.1	
AC241, 244	t_{PLH}	1.5	—	93	—	103	ns
	t_{PHL}	3.3	3	10.5	2.9	11.5	
Output Enable Times	t_{PZL}	1.5	—	136	—	150	ns
	t_{PZH}	3.3	4.6	16.4	4.5	18	
Output Disable Times	t_{PLZ}	1.5	—	136	—	150	ns
	t_{PHZ}	3.3	3.9	13.6	3.8	15	
Power Dissipation Capacitance AC240 AC241, 244	$C_{PD}\S$	—	65 Typ.		65 Typ.		pF
		—	71 Typ.		71 Typ.		
Min. (Valley) V_{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V_{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V_{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V_{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C_i	—	—	10	—	10	pF
3-State Output Capacitance	C_o	—	—	15	—	15	pF

SWITCHING CHARACTERISTICS: ACT Series; $t_r, t_f = 3 \text{ ns}$, $C_L = 50 \text{ pF}$

CHARACTERISTICS	SYMBOL	V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Outputs ACT240	t_{PLH}	5†	2.3	7.8	2.2	8.6	ns
	t_{PHL}	5†	2.3	7.8	2.2	8.6	
ACT241, 244	t_{PLH}	5	2.5	8.7	2.4	9.6	ns
	t_{PHL}	5	2.5	8.7	2.4	9.6	
Output Enable Times	t_{PZL}	5	3.5	12.2	3.4	13.4	ns
	t_{PZH}	5	3.5	12.2	3.4	13.4	
Output Disable Times	t_{PLZ}	5	3.5	12.2	3.4	13.4	ns
	t_{PHZ}	5	3.5	12.2	3.4	13.4	
Power Dissipation Capacitance ACT240 ACT241, 244	$C_{PD}\S$	—	65 Typ.		65 Typ.		pF
		—	71 Typ.		71 Typ.		
Min. (Valley) V_{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V_{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V_{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V_{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C_i	—	—	10	—	10	pF
3-State Output Capacitance	C_o	—	—	15	—	15	pF

*3.3 V: min. is @ 3.6 V
max. is @ 3 V

†5 V: min. is @ 5.5 V
max. is @ 4.5 V

‡ C_{PD} is used to determine the dynamic power consumption, per package.

For AC series: $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$

For ACT series: $P_D = V_{CC}^2 f_i (C_{PD} + C_L) + V_{CC} \Delta I_{CC}$ where f_i = input frequency

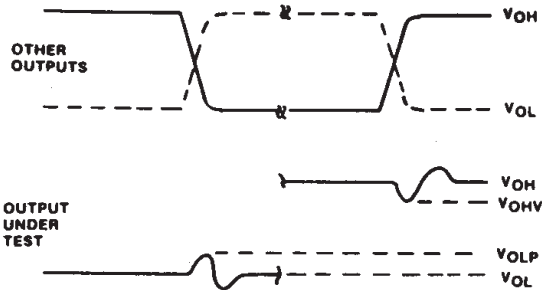
C_L = output load capacitance

V_{CC} = supply voltage.

Technical Data

CD54/74AC240/241/244 CD54/74ACT240/241/244

PARAMETER MEASUREMENT INFORMATION



- NOTES:**
1. V_{OHV} AND V_{OLP} ARE MEASURED WITH RESPECT TO A GROUND REFERENCE NEAR THE OUTPUT UNDER TEST.
 2. INPUT PULSES HAVE THE FOLLOWING CHARACTERISTICS: $PRR \leq 1$ MHz, $t_r = 3$ ns, $t_f = 3$ ns, SKEW 1 ns.
 3. R.F. FIXTURE WITH 700-MHz DESIGN RULES REQUIRED. IC SHOULD BE SOLDERED INTO TEST BOARD AND BYPASSED WITH $0.1 \mu\text{F}$ CAPACITOR. SCOPE AND PROBES REQUIRE 700-MHz BANDWIDTH.

92CS-42406

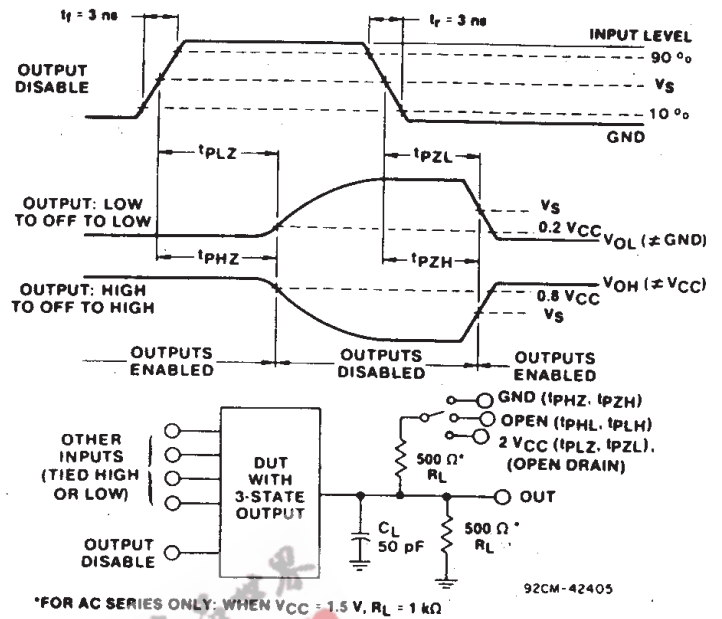


Fig. 1 - Simultaneous switching transient waveforms.

Fig. 2 - Three-state propagation delay times and test circuit.

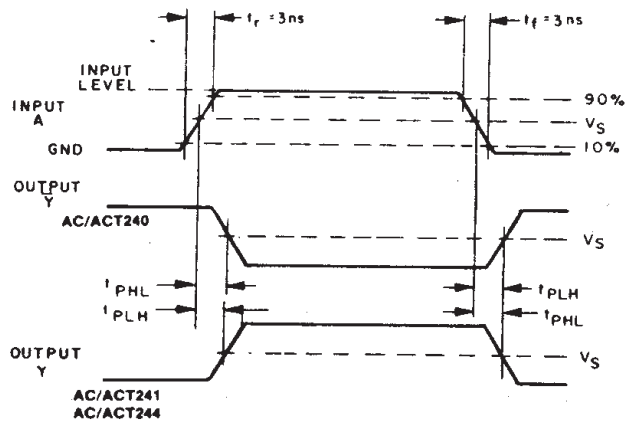
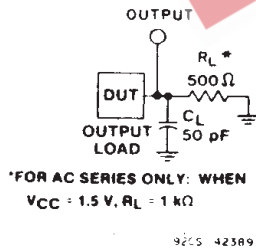


Fig. 3 - Propagation delay times and test circuit.

	CD54/74AC	CD54/74ACT
Input Level	V_{CC}	3 V
Input Switching Voltage, V_S	$0.5 V_{CC}$	1.5 V
Output Switching Voltage, V_S	$0.5 V_{CC}$	$0.5 V_{CC}$

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD54AC240F3A	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
CD54AC244F3A	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
CD54ACT240F3A	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
CD54ACT241F3A	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
CD54ACT244F3A	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
CD74AC240E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74AC240M	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74AC240M96	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74AC244E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74AC244M	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74AC244M96	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74AC244SM	OBSOLETE	SSOP	DB	20		Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74AC244SM96	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74ACT240E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74ACT240M	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74ACT240M96	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74ACT241E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74ACT241M96	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74ACT244E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74ACT244M	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74ACT244M96	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74ACT244SM	OBSOLETE	SSOP	DB	20		Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74ACT244SM96	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

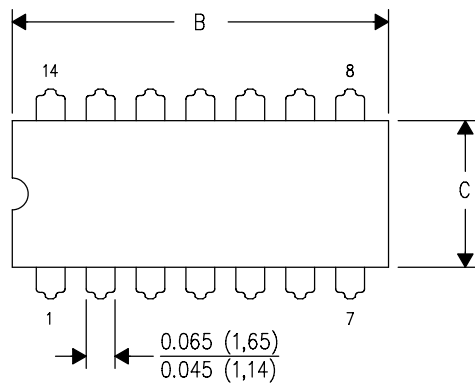
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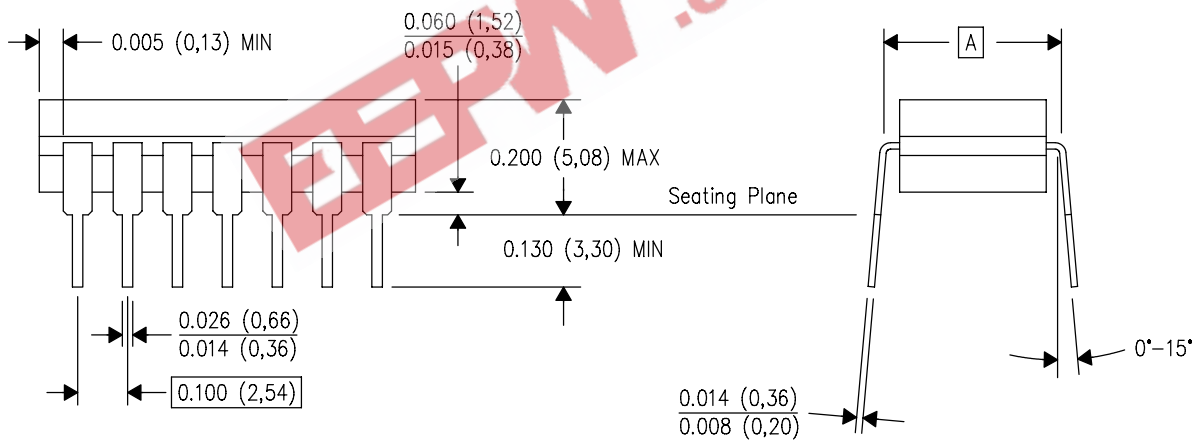
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J (R-GDIP-T**)
14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



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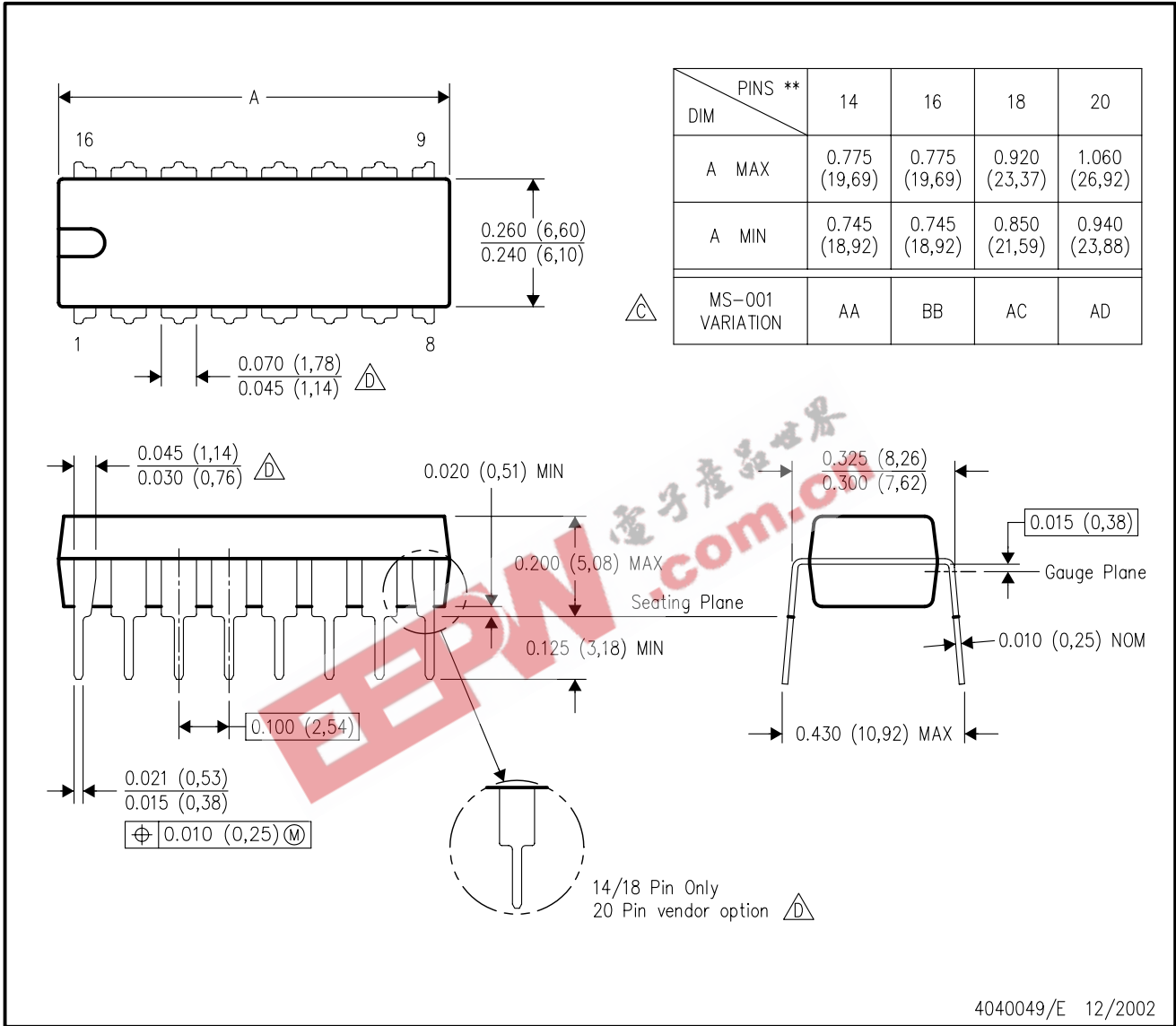
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

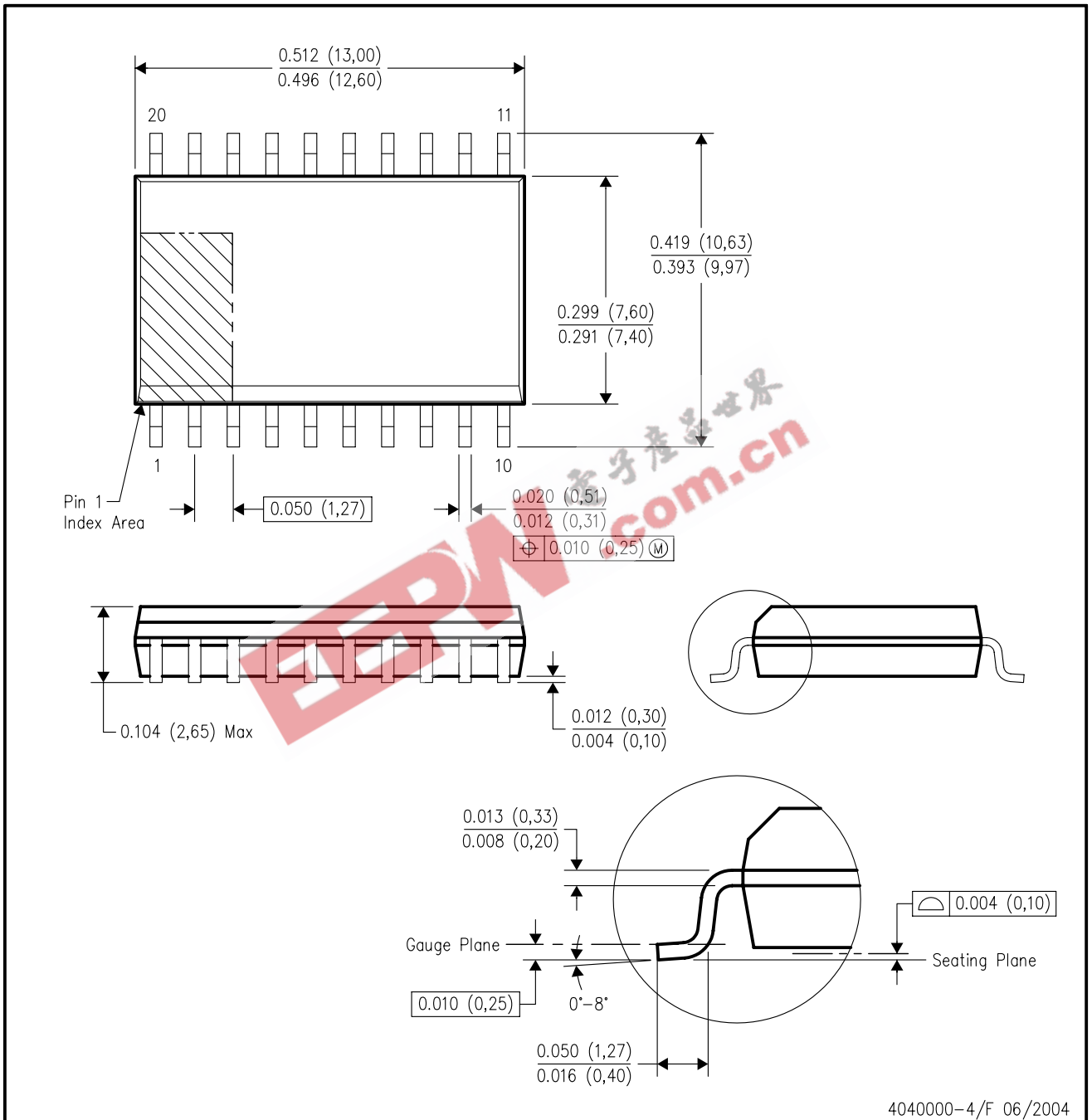


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



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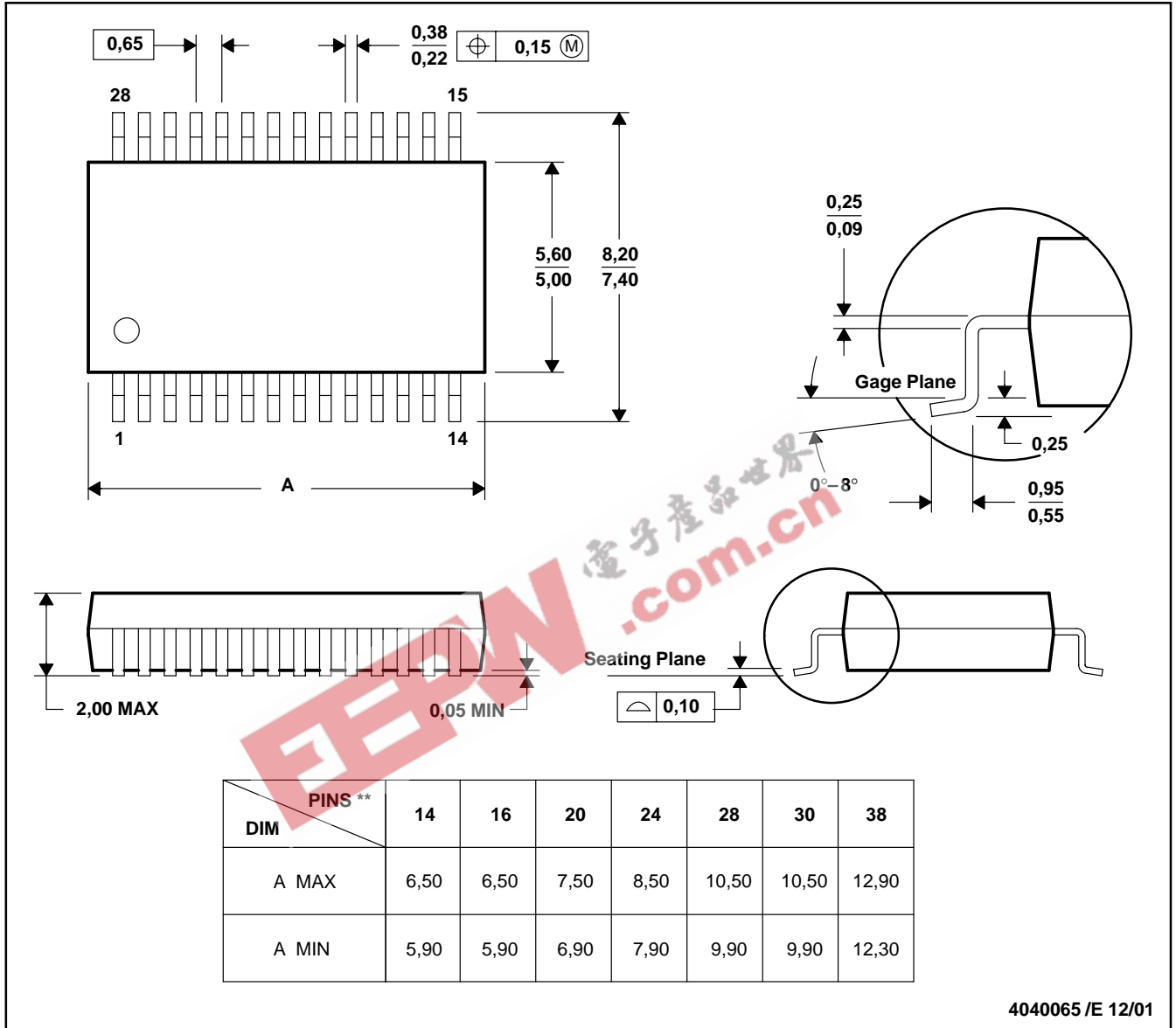
MECHANICAL DATA

MSS0002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

4040065 /E 12/01

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